

Title (en)

METHOD FOR PRODUCING A PRINTED CIRCUIT BOARD USING A MOULD FOR CONDUCTOR ELEMENTS

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER LEITERPLATTE UNTER VERWENDUNG EINER FORM FÜR LEITERELEMENTE

Title (fr)

PROCÉDÉ DE FABRICATION D'UNE CARTE DE CIRCUIT IMPRIMÉ À L'AIDE D'UN MOULE POUR ÉLÉMENTS CONDUCTEURS

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Application

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Abstract (en)

[origin: WO2019175090A1] The present invention relates to a method for producing a printed circuit board having at least one conductor element which extends between connection points in the printed circuit board. In order to increase the productivity of the known method for producing a printed circuit board having at least one conductor element which extends between connection points in the printed circuit board, the method according to claim 1 comprises the following steps: - Step A: providing a mould (3) having at least one receptacle (3c) for a conductor element (2). - Step B: arranging a conductor element (2) in the receptacle (3c) of the mould (3). - Step C: connecting the conductor element (2), which is arranged in the receptacle (3c) of the mould (3), to an electrically conductive sheet-like element (5) at positions of the intended connection points. - Step D: embedding the conductor element (2), which is connected to the electrically conductive sheet-like element (5), in insulating material (4). - Step E: working the connection points out of the electrically conductive sheet-like element (5).

IPC 8 full level

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